

**WHAT IS CLAIMED IS:**

1. A method of coating multiple layers on a support comprising
  - a) taking a support;
  - b) simultaneously coating on said support a first chill settable layer and a non-chill settable layer;
  - c) lowering the temperature of the layers to immobilize said layers; and
  - d) drying said layers.
2. The method of claim 1 wherein the resulting product is an imaging element.
3. The method of claim 2 wherein the non-chill settable layer forms an image forming unit comprising photosensitive microcapsules and a developer.
4. The method of claim 2 wherein the temperature is lowered to less than 30° C.
5. The method of claim 2 wherein the temperature is lowered to less than 20° C.
6. The method of claim 2 wherein the temperature is lowered to less than 10° C.
7. The method of claim 2 wherein the first chill settable layer is layered on top of the non-chill settable layer.
8. The method of claim 7 wherein a second chill settable layer is coated below the non-chill settable layer.

9. The method of claim 8 wherein the second chill settable layer is coated simultaneously with the non-chill settable layer and the first chill settable layer.

10. The method of claim 2 wherein the first chill settable layer comprises gelatin.

11. The method of claim 8 wherein the second chill settable layer comprises gelatin.

12. The method of claim 1 wherein the chill settable layer has a wet laydown thickness greater than 20% of the wet laydown thickness of the non-chill settable layer.

13. The method of claim 2 wherein the first chill settable layer and the non-chill settable layer are simultaneously coated with a multi-slotted slide hopper.

14. The method of claim 2 wherein the support absorbs water or wherein there is an additional layer coated on the support that absorbs water.

15. The method of claim 14 wherein there is an additional water absorbing layer coated on the support, said layer comprising gelatin.

16. The method of claim 2 wherein the non-chill settable layer is porous after drying.

17. The method of claim 2 wherein the first chill settable layer comprises sub-layers.

18. The method of claim 17 wherein chill settable sub-layers have different compositions.

19. The method of claim 18 wherein the chill settable sub-layers form an inner chill settable sub-layer and an outer chill settable sub-layer and wherein the outer chill settable sub-layer has a modulus greater than the modulus of the inner chill settable sub-layer after being coated and dried.

20. The method of claim 19 wherein the inner chill settable sub-layer has a modulus of less than 3 Gpa.

21. The imaging element of claim 19 wherein the outer chill settable sub-layer has a modulus of greater than 3 Gpa.

22. The method of claim 3 wherein the imaging element is pressure developable.

23. The method of claim 2 wherein the layers are dried at a temperature of less than 50° C.

24. An imaging element comprising a support, a non-chill settable layer and a chill settable layer wherein the non-chill settable layer is between the support and the chill settable layer and wherein the non-chill settable layer has a dry thickness of at least 10  $\mu\text{m}$ .

25. The imaging element of claim 24 wherein the non-chill settable layer is porous.

26. The imaging element of claim 24 wherein the non-chill settable layer forms an image forming unit comprising photosensitive microcapsules and a developer.

27. The imaging element of claim 26 wherein the imaging element is pressure developable.

28. The imaging element of claim 24 wherein the support absorbs water or wherein there is an additional layer on the support that absorbs water.

29. The imaging element of claim 28 wherein the additional water absorbing layer is gelatin.

30. The imaging element of claim 24 wherein the chill settable layer comprises sub-layers.

31. The imaging element of claim 30 wherein the chill settable sub-layers have different compositions.

32. The imaging element of claim 31 wherein the chill settable sub-layers form an inner chill settable sub-layer and an outer chill settable sub-layer and wherein the outer chill settable sub-layer has a modulus greater than the modulus of the inner chill settable sub-layer.

33. The imaging element of claim 24 wherein the inner chill settable sub-layer has a modulus of less than 3 Gpa.

34. The imaging element of claim 24 wherein the outer chill settable sub-layer has a modulus of greater than 3 Gpa.